

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Prindiville et al.

Art Unit: 2827

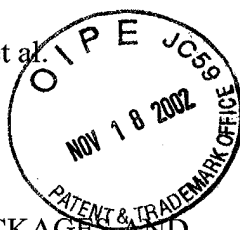
Application No.: 09/971,872

Filed: October 4, 2001

For: SEMICONDUCTOR PACKAGES AND  
METHODS FOR MAKING THE SAME


Examiner: Ishwarbhai B. Patel

Date: November 12, 2002



**CERTIFICATE OF MAILING**

I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service on November 12, 2002 as First Class Mail in an envelope addressed to: BOX NON-FEE AMENDMENT, COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231.

  
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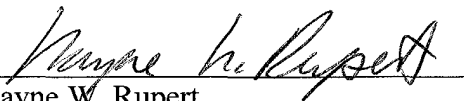
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**LETTER TO THE OFFICIAL DRAFTSPERSON**

Attached are two (2) sheets of corrected drawings (Sheet 1 of 5 and Sheet 4 of 5) for the above-identified patent application, with each sheet indicating the title, inventor's name, and application number on the front of each sheet and centered within the top margin. The corrected drawings now show the cross hatching patterns based on a particular material for each part.

Respectfully submitted,

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